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Advanced Packaging Materials and Evaluation Platform at Resonac

Senior Director Hidenori Abe

Electronics Business Headquarters

Resonac Corporation, Japan



- He is leading R&D of semiconductor materials in general and promoting co-creation activities at Resonac, which is an integrated company of Showa Denko K.K. and Showa Denko Materials Co., Ltd., (formerly Hitachi Chemical Co., Ltd.), after serving as a General manager of CMP slurry business sector and a corporate marketing manager at Hitachi Chemical.
- He was involved in the launch of the Packaging Solution Center, which is open innovation hub in advanced packaging development.
- He had been engaged in the development of semiconductor molding compounds since 1998.
- · He holds an Executive MBA from Oxford, UK.